

Docket No.: 2336-247

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Joo Ho LEE et al.

Confirmation No. 2626

U.S. Patent Application No. 10/790,723

Group Art Unit: 2826

Filed: March 3, 2004

Examiner: Fetsum Abraham

For: WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD THEREOF

## RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents P.O. Box 1450 Alexandria VA 22313-1450

Sir:

By Official Action mailed February 25, 2005, restriction to one of the following inventions is required:

Group I: Claims 1-10, drawn to a package with via contacts, classified in class 257, subclass 774.

Group II: Claims 11-22, drawn to a method of making a semiconducting package with via contacts, classified in class 438, subclass 629.

In response, Applicants hereby elect Group I, upon which claims 1-10 are readable.

The election was made *with traverse* because the search and examination of the entire application can be made without serious burden on the Examiner. Inventions II and I are related as